

Quad Differential Backplane Transceiver

Advanced Micro **Devices**

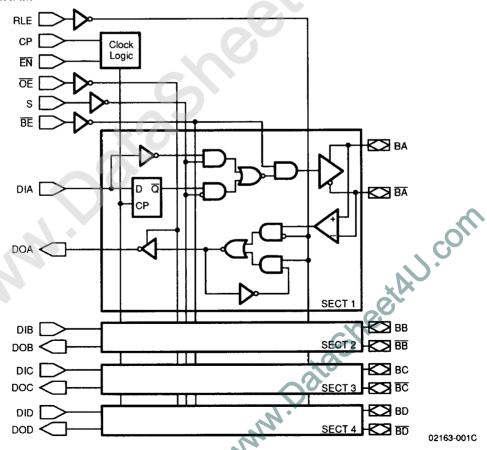
DISTINCTIVE CHARACTERISTICS

- 10 Mb data rate
- 0.45 V DC noise margin
- Biasing line terminations allow low voltage swing while maintaining high noise margin
- Pair delay 55 ns maximum
- Controlled driver skew to minimize noise
- Driver register and receiver latch with register bypass mode
- Driver output short-circuit protected to Vcc
- Outputs disabled during power-up and down
- Three-state receiver outputs maintain Hi-Z during power-up and down and over Vcc range

GENERAL DESCRIPTION

The Am26LS38 is a high performance backplane transceiver designed to integrate Schottky TTL performance, high noise immunity and wired logic capability into a low cost differential backplane structure. The resulting backplane can have up to 24 receiver unit loads in a party-line, wired-OR logic configuration, with a guaranteed fail-safe state, and operates from a single 5 V power supply.

BLOCK DIAGRAM

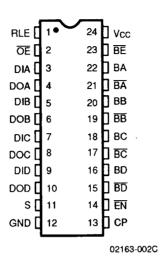


02163-001C

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CONNECTION DIAGRAM Top View

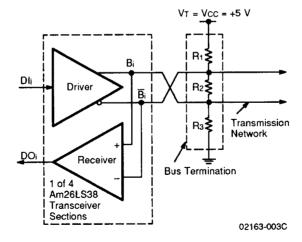
DIP



Note:

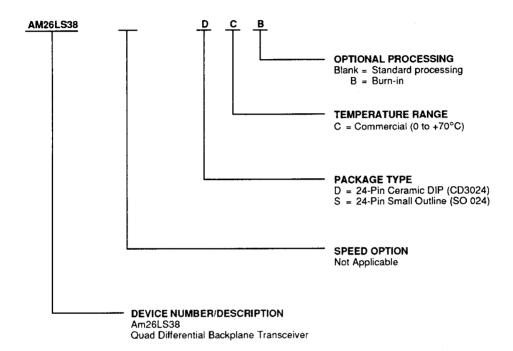
Pin 1 is marked for orientation.

SYSTEM CONFIGURATION DIAGRAM



ORDERING INFORMATION Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:



Valid Combinations							
AM26LS38	DC, DCB, SC						

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.



PIN DESCRIPTION

THE DESCRIPTION								
Pin No.	Name	I/O	Description					
22, 20 18, 16, 21, 19, 17, 15	BA, BB, BC, BD (B), BA, BB, BC, BD (B)	1/0	Paired open emitter (B _i)/ open collector (\overline{B}_i) driver outputs and receiver inputs. The driver outputs are either simultaneously active or simultaneously inactive. In the inactive state (Dl _i = LOW) both drivers (B _i and \overline{B}_i) are turned off and the voltage differential representing the OFF state is determined by the line terminating resistor networks. In the active state (Dl _i = HIGH), both drivers are driven on and act to reverse the voltage differential across the line to produce the ON state. The open-emitter/open-collector outputs are always connected in a wried-OR (or wired-AND) configuration. A driver is disabled by making its outputs inactive.					
23	BE	-	Bus Enable operates to enable or disable all output drivers by making them inactive when \overline{BE} = HIGH and controlled by data input when \overline{BE} = LOW.					
13	СР	1	Clock Pulse input to the driver register enters data on the LOW-to-HIGH transition.					
3, 5, 7, 9	DIA, DIB, DIC, DID (DI;)	ı	Data inputs each driver's buffer or register. A HIGH input to DI will result in an active (ON) output. A LOW input will cause an inactive (OFF) output.					
4, 6, 8, 10	DOA, DOB, DOC, DOD (DOi)	0	Receiver data latch outputs. An inactive bus (OFF state) will produce a LOW DO output and an active bus (ON state) will produce a HIGH DO output.					
14	ĒN	I	Clock Enable for the driver registers. \overline{EN} = LOW enables DI data to be clocked into the respective register. \overline{EN} = HIGH acts to hold previous data in each register regardless of the state of CP.					
2	ŌĒ	1	Output Enable for the receiver latch output buffer. When \overline{OE} is LOW the outputs are enabled. When \overline{OE} is HIGH all receiver outputs are in the high impedance state.					
1	RLE	ı	Receiver Latch Enable for the receiver latches. When RLE is HIGH the latches are transparent. When RLE is LOW received data meeting the setup and hold requirements relative to the HIGH-to-LOW transition of RLE will be stored.					
11	S	1	Select input control for the drivers. When S is HIGH driver data from the registers will be selected (Register Mode). When S is LOW (Buffer Mode) the drivers respond to the DI inputs directly, bypassing the driver registers.					

				Input	S				(Outpu	ts	
RLE	СР	EN	ŌĒ	s	BE	Dli	Bi	Bi	Bi	Bi	DOi	Function
Н	Х	Х	L	L	L	L	NA	NA	L	Н	L	Driver buffer mode (loop test)
Н	Х	Х	L	L	L	Н	NA	NA	Н	L	Н	
Н	1	L	L	Н	L	L	NA	NA	L	Н	L	Driver register mode
Н	1	L	L	Н	L	Н	NA	NA	Н	L	Н	
H	Х	Х	L	Х	Н	Х	L	Н	NA	NA	L	Receiver latch mode
Н	Х	Х	L	Х	Н	х	н	L	NA	NA	Н	
L	Х	Х	L	Х	Н	Х	Х	Х	Х	Х	DOin-1	Receiver in circulation
Х	х	х	Н	Х	Н	Х	×	х	Х	Х	Z	Receiver output in high impedance state

H = HIGH

L = LOW

↑ = LOW-to-HIGH transition of clock

DOin-1 = Previous state of DOi

Z = High impedance

X = Don't care

NA = Not applicable

FUNCTIONAL DESCRIPTION

The Am26LS38 represents a new approach in backplane transceiver design. Its unipolar differential signaling scheme minimizes problems associated with crosstalk and the loss of noise immunity due to common mode voltage while providing high speed, party line and wired logic capabilities.

A good ground system and shielding are the best methods for limiting noise on the backplane. Ground planes can significantly reduce inductive ground voltage ringing. Where multilayer PC backplane are not a reasonable choice, a differential bus can be created using the Am26LS38 and twisted pair or any balanced transmission medium.

A backplane designed with an Am26LS38 has 3 main elements; 1) a driver section, 2) a receiver section, 3) and a controlled impedance differential line with a prebiasing line termination. The scheme for driver, receiver, and termination resistors is shown in Figure A.

System Operation

The system has two operational states.

- 1. Active driver outputs on
- 2. Passive driver outputs off

This 2-state (active/passive) operation makes passive or wired logic functions possible. In the passive state, the lines assume a known polarity and voltage (pre-biased bus). The passive bus state may be assigned either the false (wired-OR) or true (wired-AND) sense, potentially reducing the number of backplane signal lines.

The 2-state driver employs active pull-down (open collector) and active pull-up (open emitter) output stages (Figure A). When a driver is active, both output stages turn on. This impresses a 0.5 V minimum voltage differential on the bus, reversing the voltage across R₂. In the passive mode both output stages are off. The voltage levels and polarities return to the conditions set by the pre-biasing resistive network. In either state the voltage across the differential lines are symmetrical about Vcc/2. The system achieves high speeds because the

voltage levels required to change state are very close together.

The receiver is designed with a ± 50 mV threshold voltage. This low threshold level combined with a driver output greater than 500 mV provides a high degree of tolerance to attenuation and reflection effects in the cable. Receiver hysteresis provides differential noise immunity. Without hysteresis, a small amount of noise around the switching threshold could cause errors.

Propagation delay skew (tphl – tplh) is controlled. The system allows up to 1.5 V of common mode voltage.

Terminating the Transmission Line or Bus

Common mode reflections in the line can be reduced significantly by symmetrically terminating the bus. This increases the tolerance to common mode noise. Centering the network at Vcc/2 (R₁ = R₃) further improves the performance by causing all induced noise and reflections to appear as a common mode signal (Figure B).

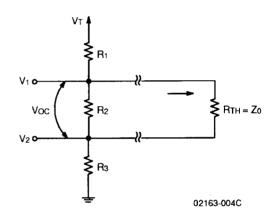
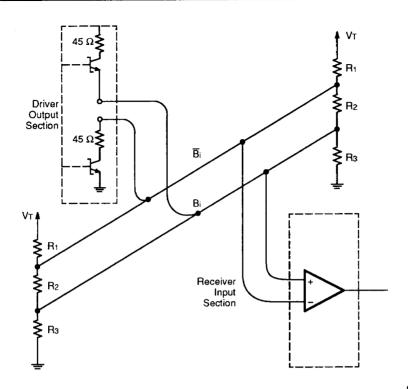


Figure B. Termination Circuit



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Figure A. The Scheme for Driver, Receiver, and Termination Resistors

A first order approximation of resistor values may be developed by letting the ratio of R_1 to R_2 be 2:1, and the Thevenin equivalent resistance of the termination equal the characteristic impedance of the line (Z_0) .

Then:

(1)
$$Voc = V_T \frac{R_2}{R_2 + 2R_1}$$

(2)
$$R_{TH} = \frac{2R_1R_2}{2R_1 + R_2}$$

From equation (1) and (2),

(3)
$$R_1 = \frac{V_T R_{TH}}{2V_{OG}}$$

(4)
$$R_2 = \frac{V_T R_{TH}}{V_T - V_{QC}}$$

If V_T = 5 V, V_{OC} = 1.0 V, and R_{TH} = 90Ω = Z₀, we can derive that R₁ ~220 Ω , R₂ ~110 Ω .

Second order adjustments require attention to unit loading factors (receiver differential input resistance is in parallel with R₂), transmission rates and a host of other factors.

Data Path

Figure C shows the data path from one driver to another receiver for one bit of the bus interface.

The transmit register or buffer and receiver latch are configured to provide two modes of operation. The register and latch can provide local storage for output and input data. In the non-storage mode the buffer input to the driver can be selected and the receiver can be wired transparent. Incorporating storage on-chip provides improved speed and lower package count without significant penalty in the non-storage mode.

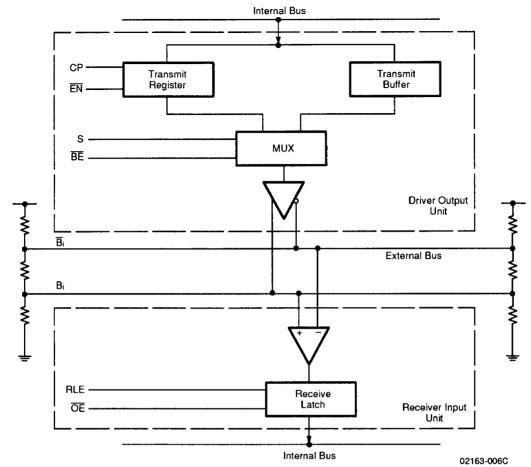
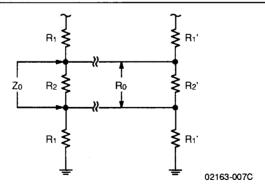


Figure C. The Data Path for One Bit of the Bus Interface



Equivalent Circuit Recommended Termination

Termination Resistors and Equivalent Impedance

Zo	R ₁ = R ₁ '	$R_2 = R_2$
90Ω	220Ω	110Ω
120Ω	300Ω	150Ω

Minimum line Vo (differential voltage) = 0.5 V

Equivalent Termination Versus DC Resistance

-	Zo	R₀
	88.0Ω	44.0Ω
	120.0Ω	60.0Ω



ABSOLUTE MAXIMUM RATINGS

Supply Voltage 7.0 V
Common Mode Range 0 to Vcc
Differential Mode Range (REC) 0 to Vcc
Logic Inputs 5.5 V
Storage Temperature Range -65 to +150°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Temperature 0 to $+70^{\circ}$ C Supply Voltage +4.75 V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Condition	ıs	Min.	Тур.	Max.	Unit
Bus Driver	Output						
Vo	Output Differential Voltage (Driver Active) V _{Bi} – V _{Bi}	BE = LOW DI _i = Test Circuit #1	0.5			٧	
lss	Output Current	DIi = HIGH	la	-22.5	<i>–</i> 55	-115	A
	'	Test Circuit #2 BE = LOW	lb	+22.5	+55	+115	mA
Isc	Output Short Circuit Current	Vcc = 5.5 V		-75	-150	250	mA
Bus Receiv	er Input						
Vтн	Differential Input Threshold Voltage	Vout = 0 to Vcc	У он	-50	±10	+50	m∨
Rin	Input Resistance to GND	0 ≤ Vcc ≤ Vcc	Max.	4	5.7		kΩ
Rin	Differential Input Resistance	0 ≤ Vcc ≤ Vcc	Max.	8	11.4		kΩ
Vos	Center Voltage	Test Circuit #3	Active and Passive	2.0	Vcc/2	3.0	V
Vos - Vos	Center Voltage Difference (Active vs Passive)	Test Circuit #3		90	300	mV_	
Non-Bus Ir	put and Outputs						
	O. Arvit I II O. I. Veltogo	$\Delta V_{IN} = +0.1 V$	I _{OH} = -15 mA	2.4	3.4		l _v
Vон	Output HIGH Voltage	∆VIN = +0.1 V	1он = - 24 mA	2.0	3.3	2.5	
Vol	Output LOW Voltage	ΔVIN = −0.1 V	MIL, $lo_L = 32 \text{ mA}$ COM'L, $lo_L = 48 \text{ mA}$			0.5 0.5	v
ViH	Input HIGH Voltage	Guaranteed In Voltage for All	put Logical HIGH	2.0		0.0	٧
VIL	Input LOW Voltage	Guaranteed In Voltage for All	put Logical LOW Inputs			0.8	٧
			Data		-275	-400	μΑ
1 _Մ	Input LOW Current	VIN = 0.4 V	Control		-0.65	-1.0	mA
			Clock		-0.65	-1.0	mA
liн	Input HIGH Current	V _{IN} = 2.7 V			0.1	+50	μΑ
Isc	Output Short Circuit Current	Vcc = 5.5 V		-75	-150	-250	mA
lı	Input Leakage Current	V _{IN} = 5.5 V				1	mA
Vic	Input Clamp Voltage	I _{IN} = -18 mA			-0.75	-1.2	V
		$V_0 = 2.4 \text{ V}$	<u> </u>	ļ <u> </u>	+50	μA	
loz	Leakage Current Passive	$V_0 = 0.4 \text{ V}$			<u> </u>	-50	
Icc	Power Supply Current	BE, OE = HIGH	<u> </u>	L	145	mA	

SWITCHING CHARACTERISTICS (T_A = +25°C, V_{CC} = 5.0 V)

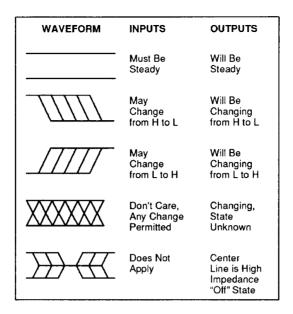
Parameter Symbol	Parameter Description	Test Conditio	ns	Min.	Тур.	Max.	Unit	
toba	Dli to Bi/Bi Propagation	Active	BE = LOW	BE = LOW		7	10	
tosp	Delay	Passive	S = LOW	Test Circuit #1		7	10	ns
tcba	CP to Bi/Bi Propagation	Active	BE = LOW	T1 0: 11 414		10.5	16	ns
tcbp	Delay	Passive	S = HIGH	Test Circuit #1		13	16	115
t PA	BE to Bi/Bi Propagation	Active	Dli = HIGH	To at Oires it #4		8.5	12	ns
tpp	Delay	Passive	S = LOW	Test Circuit #1		4	8	
ts	Dli to Clock Setup Time				5	2.5		
tн	Dli to Clock Hold Time				2	0		
ts	EN to Clock Setup Time		BE = LOW		8	4		ns
tн	EN to Clock Hold Time		BL = LOW		0	-4		113
ts	Bi/Bi to RLE Setup Time]		5	2.5		
tн	Bi/B̄i to RLE Hold Time				2	0.7		
tplz/tpHz	<u> </u>		C _L = 50 pF	Test Circuit #4			20	na
tplz/tpHz	OE to DOi Disable Time		C _L = 5 pF	Test Circuit #4			13	ns
t PZL	OF to DO Disable Time	Test Circuit #4				17	ns	
tezh	OÈ to DOi Disable Time	Test Circuit #4			17			
t PLH	RLE to DO		OE = LOW Test Circuit #4		11	13	ns	
t PHL	ALE IO DO				14	17		
tpax	Bi/Bi to DOi		RLE = HIGH OE = LOW	Test Circuit #4		12	17	ns
t PLH	5E		RLE = HIGH	Test Circuits		15	25	ns
TPHL	BE to DOi Propagation Do	eiay	OE = LOW	#1, #4		15	25	113
tрцн	Dli to DOi (Buffer Mode)		S = LOW RLE = HIGH	Test Circuits		18	25	ns
tphL	Dir to DOI (Daner Mode)		OE = LOW	#1, #4			20	
t _{PLH}	CD to DO (Dociotos Mod	- >	S = HIGH	Test Circuits		00	00	ns
t PHL	CP to DOi (Register Mode	e) 	RLE = HIGH OE = LOW	#1, #4		22	28	112
t PWL	Clock Pulse Width	LOW			10	3		
tрwн	HIGH				10	5		ns
tрwн	RLE Pulse Width	HIGH			10	6		ns
tskew	Propagation Delay Skew (tplh – tphl)	7.1	Vcc = 5 V C _L = 50 pF Measurement	Test Circuit #1		±1	±5	ns



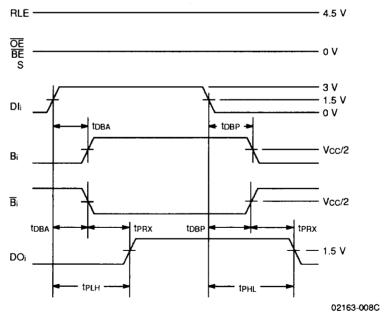
SWITCHING CHARACTERISTICS over operating range unless otherwise specified

				T _A = 0 to V _{CC} = 5.0			
Parameter Symbol	Parameter Description		Test Conditi	Min.	Max.	Unit	
toba	DIi to Bi/ Bi Propagation	Active	BE = LOW	Test Circuit #1		12	ns
tobp	Delay	Passive	S = LOW			12	113
tcba	CP to Bi/ Bi Propagation	Active	BE = LOW	Test Circuit #1		20	ns
t CBP	Delay	Passive	S = HIGH			20	
t _{PA}	BE to Bi/ Bi Propagation	Active	Dli = HIGH	Test Circuit #1		17	ns
tpp	Delay	Passive	S = LOW			12	
ts	Dli to Clock Setup Time				7		
tн	Dlito Clock Hold Time				3		
ts	EN to Clock Setup Time		BE = LOW		10		ns
tн	EN to Clock Hold Time		BC = LOW		0		
ts	B _i / B̄ _i to RLE Setup Time				7		
tн	B _i / B _i to RLE Hold Time				3		
tpLz/tpHz	OF to DO Disable Time		C _L = 50 pF	Test Circuit #4		17	ns
tplz/tpHz	OE to DOi Disable Time		C _L = 5 pF	Test Circuit #4		10	
t PZL	OF L BO SHALL TIME		Test Circuit #4			15	ns
tрzн	OE to DOi Enable Time		Test Officult #4			15	
tрцн	2151 22		OE = LOW	Test Circuit #4		15	ns
t PHL	RLE to DOi		OL = LOW			20	
tpax	Bi∕ B̄i to DOi		RLE = HIGH OE = LOW	Test Circuit #4		21	ns
t _{PLH}	BE to DO _i Propagation		RLE = HIGH	Test Circuits		32	ns
t _{PHL}	Delay		OE = LOW	#1, #4		<u> </u>	
t _{PLH}			S = LOW	Test Circuits			
11 (11	DIi to DOi (Buffer Mode)		RLE = HIGH	#1, #4		30	ns
t _{PHL}			OE = LOW		ļ	ļ	
tpLH			S = HIGH	Test Circuits			
tphL	CP to DOi (Register Mode)		RLE = HIGH OE = LOW	#1, #4		35	ns
tpw.		LOW			10		
tpwh	Clock Pulse Width	HIGH	1		10		ns
tpwH	RLE Pulse Width	HIGH			13		ns
tskew	Propagation Delay Skew (tp.h – tph.)	i riidri	Vcc = 5 V CL = 50 pF Measurement \	Test Circuit #1		±7	ns

KEY TO SWITCHING WAVEFORMS

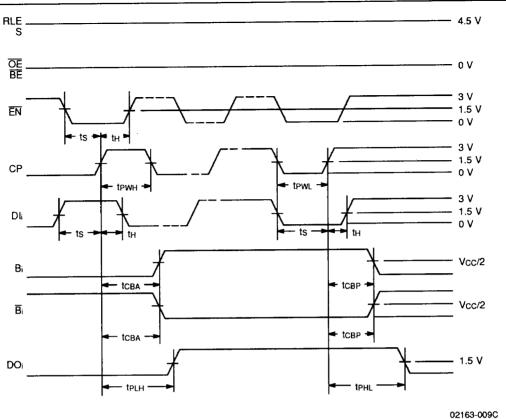


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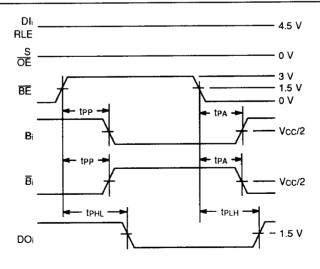


Dli to Bi, Bi, DOi (Buffer Mode)



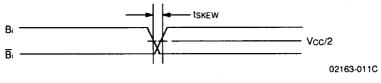


CP to Bi, Bi, DOi (Register Mode)

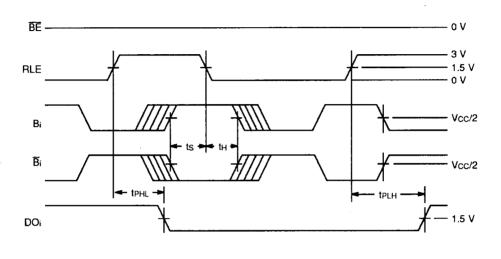


 \overline{BE} to $B_i, \overline{B}_i,$ DOi (Passive and Active)

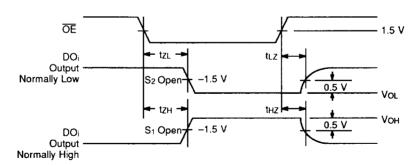
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Output to Output



RLE to DOi

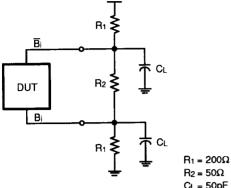


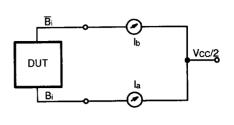
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OE to DOi

SWITCHING TEST CIRCUITS





Test Circuit #2

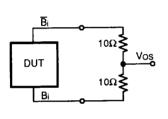
 $R_2 = 50\Omega$

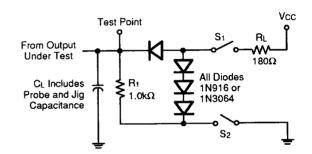
CL = 50pF

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02163-015C

Test Circuit #1





02163-017C

02163-016C

Test Circuit #3

Test Circult #4

Notes:

- 1. C_L = 50 pF unless otherwise specified.
- 2. S1 and S2 are closed except where shown.